

IN THE CLAIMS:

Claims 1, 4, 6, and 9 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor assembly comprising:
a substrate having a plurality of circuits on a portion of a surface thereof;
a semiconductor die having a plurality of bond pads located on an active surface thereof and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a gel elastomer contacting at least a portion of the back side surface of the semiconductor die, the gel elastomer comprising a compliant[,] adhesive[,] filled with a thermally conductive material; and
a heat sink cap having a portion thereof contacting a portion of the substrate covering the gel elastomer, the semiconductor die, the plurality of solder balls, the substrate, the heat sink cap contacting at least a portion of the gel elastomer.
2. (Original) The semiconductor assembly of claim 1, wherein the heat sink cap includes a plurality of fins thereon.
3. (Original) The semiconductor assembly of claim 1, wherein the gel elastomer includes a cross-linked silicone.

4. (Currently Amended) A semiconductor assembly comprising:
a substrate having a surface having a plurality of circuits on a portion thereof;
a semiconductor die having a plurality of bond pads located on a first portion of an active surface thereof and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a gel elastomer contacting a portion of the back side surface of the semiconductor die, the gel elastomer comprising a cross-linked silicone gel[[,]] filled with a thermally conductive material; and
a heat sink cap having the substrate and a portion of the gel elastomer, the heat sink cap covering the gel elastomer, the semiconductor die, the plurality of solder balls, and portion of the substrate.

5. (Original) The semiconductor assembly of claim 4, wherein the heat sink cap includes a plurality of fins thereon.

6. (Currently Amended) An assembly comprising:
a substrate having a plurality of circuits on a portion thereof;
a semiconductor die having a plurality of bond pads located thereon and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a compliant[[,]] adhesive[[,]] filled with a thermally conductive material[[,]] gel elastomer contacting at least a portion of the back side surface of the semiconductor die; and

a heat sink cap having the substrate covering the compliant[[,]] adhesive, a thermally conductive material[[,]] gel elastomer, the semiconductor die, the plurality of solder balls, a portion of the substrate, the heat sink cap contacting at least a portion of the gel elastomer.

7. (Original) The semiconductor assembly of claim 6, wherein the heat sink cap includes a plurality of fins thereon.

8. (Previously Presented) The semiconductor assembly of claim 6, wherein the compliant, adhesive, and filled with a thermally conductive material, gel elastomer includes a cross-linked silicone.

9. (Currently Amended) An assembly comprising:
a substrate having a plurality of circuits on a portion thereof;
a semiconductor die having a plurality of bond pads and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a compliant[[,]] adhesive[[,]] filled with a thermally conductive material[[,]] gel elastomer contacting a portion of the back side surface of the semiconductor die, and
a heat sink cap having the substrate and a portion of the compliant adhesive, a thermally conductive material gel elastomer, the heat sink cap covering the compliant adhesive, gel elastomer, the semiconductor die, the plurality of solder balls, and at least a portion of the substrate.

10. (Original) The semiconductor assembly of claim 9, wherein the heat sink cap includes a plurality of fins thereon.